

Notice of References Cited	Application/Control No. 10/783,462	Applicant(s)/Patent Under Reexamination FILIPPI ET AL.	
	Examiner Steven J. Fulk	Art Unit 2891	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-2003/0082901	05-2003	Werner et al.	438/618
	C	US-5,930,587	07-1999	Ryan, Vivian W.	438/14
	D	US-6,022,750	02-2000	Akram et al.	438/18
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	L	US-			
	M	US-			

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NON-PATENT DOCUMENTS

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	U	Ogawa et al., "Stress-Induced Voiding Under Vias Connected to Wide Cu Metal Leads," IEEE/IRPS, April 2002, pp. 312-321.
	V	Huston et al., "Reliability Defect Detection and Screening During Processing - Theory and Implementation," IEEE/IRPS, January 1992, pp. 268-275.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.